



2026 IEEE International Symposium on Radio-Frequency Integration Technology (RFIT2026)

24-26 August 2026, Yehliu, New Taipei City, Taiwan

First Call for Papers

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Conference Secretariat

Chiu-Chih Chou, NCU, *Taiwan*

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The 2026 IEEE International Symposium on Radio-Frequency Integration Technology (RFIT2026) will be held at Yehliu, in New Taipei City, Taiwan from August 24-26, 2026. This conference is sponsored by the IEEE Microwave Theory and Techniques Society (MTT-S) and organized by the IEEE MTT-S. It will also be supported by IEEE MTT-S Taipei Chapter and Tainan Chapter. The Taiwan Electromagnetic Industry-Academia Consortium (TEMIAC) is a Technical Co-Sponsors of RFIT2026.

Topics of interest include but not limited to

- Device Technologies: CMOS, SOI, LDMOS, SiGe, GaAs, InP, GaN, MEMS, reliability, characterization
- Modeling and CAD: active/passive device modeling, CAD, EM simulation, co-simulation
- Packaging Technologies: MCM, SiP, TSV, flip chip assembly, wire bonding, anisotropic conductive film
- Passive Circuits and Antennas: on-chip antennas, integrated passive devices, ferrite, piezoelectric material
- Frequency Generation and Conversion ICs: VCOs, PLLs, synthesizers, ADPLLs, frequency dividers/multipliers, mixers
- Front-end RFICs: LNAs, VGAs, phase shifters, RF switches
- Power ICs: power amplifiers, linearization circuits, drivers
- Millimeter-wave and THz ICs: circuits operating at mm-wave (30-300 GHz) and sub-mm-wave (>300 GHz) bands
- Analog and Mixed Signal ICs: ADC, DAC, comparators, filters, AGC/VGA
- High-Speed Data Transceivers: wireless/wireline/optical transceivers, CDRs for high-speed data links
- Power Transmission ICs: RFIDs, electric coupling, electromagnetic induction, magnetic resonance, wireless power transmission ICs
- Emerging ICs: power management, digital RF circuits/architectures, RF BIST, reconfigurable and tunable ICs, vehicle electronic ICs
- Radio-Integrated Systems: IoT/M2M, automotive radars, wearable devices, security, biomedical and health care applications
- 5G/B5G/6G Systems: MIMO systems, smart radio systems, cube satellite, and satellite communication systems

Paper submission

To encourage timely reporting of the latest results and provide better opportunities for expanding papers for possible journal publications, prospective authors are invited to submit a 2- or 3-page manuscript (both initial submission and final manuscript, if accepted) in English and in IEEE PDF eXpress format. The manuscript should emphasize original contributions and key findings, including figures, diagrams, and results from both simulations and measurements. References should be clearly cited and up-to-date. Accepted papers will be submitted to IEEE Xplore. By submitting a manuscript, the authors agree that, if accepted, at least one author will make a full registration and attend the RFIT2026 to present their paper.

Manuscript Submission Deadline:

April 15, 2026

Notification of Acceptance:

June 7, 2026

Submission of Final Manuscript:

June 30, 2026

All submission must be made through the RFIT2026 website: <https://rfit2026.org>

